



Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 57195
Application ID: 10686486
Title of Invention: APPARATUS FOR ELECTRO
CHEMICAL DEPOSITION OF
COPPER METALLIZATION WITH
THE CAPABILITY OF IN-SITU
THERMAL ANNEALING
First Named Inventor: ROBIN CHEUNG
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-10-15
Effective Receipt Date: 2004-03-16
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 8014
Attorney Docket Number: AMAT3421C2
Total Fees Authorized: 180.0
Payment Category: Deposit Account
Deposit Account Number: 200782
Deposit Account Name: N. Alexander Nolte
Access Code: *****
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2004-03-16
RAM Sequence Number: 16




Digital Certificate Holder: cn=N. Alexander Nolte,ou=Registered Attorneys,ou=Patent and
Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: 79a2cccee8464255fb08817a8b9cb2d835a59d05



TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING															
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Date: 2003-10-15																
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<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mr. N. ALEXANDER NOLTE Registered Number: 45689</td><td>[N. ALEXANDER NOLTE]</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mr. N. ALEXANDER NOLTE Registered Number: 45689	[N. ALEXANDER NOLTE]	Attorney								
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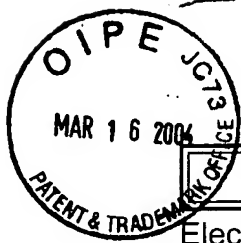
Comments

**FEE TRANSMITTAL**

Electronic Version v08


Stylesheet Version v08.0

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Application Number: 10/686486 											
Date: 2003-10-15											
First Named Applicant: ROBIN CHEUNG											
Attorney Docket Number: AMAT3421C2											
Art Unit: 1753											
TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
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Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 200782											
Access Code *****											
Deposit name: Moser Patterson Sheridan											
Deposit authorized name: N. Alexander Nolte											
Signature: /N. Alexander Nolte/											
Date (YYYYMMDD): 2004-03-16											



FEE TRANSMITTAL

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF
COPPER METALLIZATION WITH THE CAPABILITY OF IN-
SITU THERMAL ANNEALING

Application Number: 10/686486



Confirmation Number: 8014

First Named Applicant: ROBIN CHEUNG

Attorney Docket Number: AMAT3421C2

Art Unit: 1753

Search string: (2026605 or 4265943 or 4786337 or 5156731
or 5384284 or 5510216 or 5846598 or 5885749
or 5891513 or 5907790 or 5913147 or 5994675
or 6017777 or 6030208 or 6037257 or 6171922
or 6174388 or 6207937 or 6211495 or 6222164
or 6242349 or 6258223 or 6290833 or 6296906
or 6483081 or 6544338 or 5431700 or 6072163
or 6307184 or 6423947 or 6529686 or 6639189
or 20020004301 or 20020102837 or
20030045095).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	2026605	1936-01-07	ANTISELL			
	2	4265943	1981-05-05	GOLDSTEIN, ET AL.			
	3	4786337	1988-11-22	MARTIN			
	4	5156731	1992-10-20	OGASAWARA, ET AL.			
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	7	5846598	1998-12-08	SEMKOW, ET AL.			
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	11	5913147	1999-06-15	DUBIN, ET AL.			



	12	5994675	1999-11-30	BETHUNE, ET AL.
	13	6017777	2000-01-25	KIM, ET AL.
	14	6030208	2000-02-29	WILLIAMS, ET AL.
	15	6037257	2000-03-14	CHIANG, ET AL.
	16	6171922	2001-01-09	MAGHSOUDNIA
	17	6174388	2001-01-16	SIKKA, ET AL.
	18	6207937	2001-03-27	STODDARD, ET AL.
	19	6211495	2001-04-03	STODDARD, ET AL.
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	21	6242349	2001-06-05	NOGAMI, ET AL.
	22	6258223	2001-07-10	CHEUNG, ET AL.
	23	6290833	2001-09-18	CHEN
	24	6296906	2001-10-02	STIMMELL, ET AL.
	25	6483081	2002-11-19	BATCHELDER
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	27	5431700	1995-07-11	SLOAN
	28	6072163	2000-06-06	ARMSTRONG, ET AL.
	29	6307184	2001-10-23	WOMACK, ET AL.
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	31	6529686	2003-03-04	RAMANAN, ET AL.
	32	6639189	2003-10-28	RAMANAN, ET AL.

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020004301	2002-01-10	CHEN, ET AL.			
	2	20020102837	2002-08-01	RITZDORF, ET AL.			
	3	20030045095	2003-03-06	RITZDORF, ET AL.			

Signature

Examiner Name	Date